

Board Level Cooling – Surface Mount 5731



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Surface Mount 5731 is a series of surface mount board level heat sinks designed to cool Dual Flat No-Leads (DFN) packages, Quad Flat No-Leads (QFN) packages and D2 Pak (TO-263) devices. Surface Mount 5731 can cool either a single D2 Pak, larger QFNs or DFNs, or multiple QFNs or DFNs. The tin plated surface of Surface Mount 5731 enables direct soldering to Printed Circuit Boards (PCBs) for effective board cooling.

573100D00000G is the bulk packaging option of Surface Mount 5731 and 573100D00010G is the tape and reel offering for high volume manufacturing. Representative image only.



ORDERING INFORMATION

| Part Number | Device Type |
|---------------|---------------|
| 573100D00000G | D-Pak, TO-252 |
| 573100D00010G | D-Pak, TO-252 |

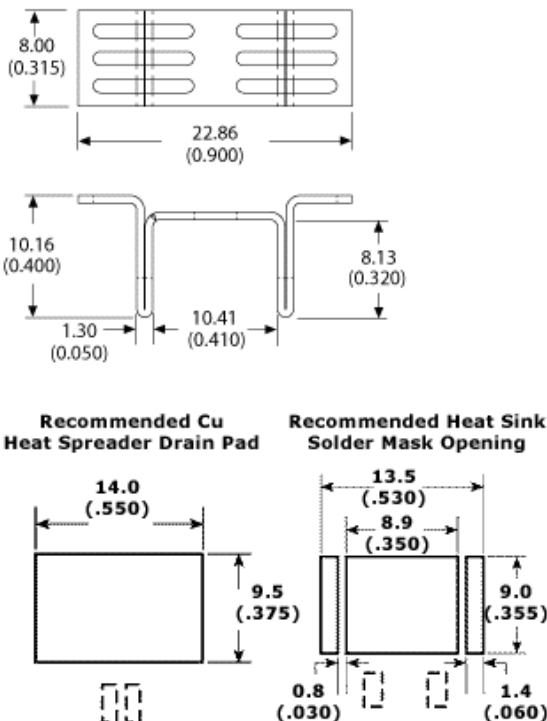
HEAT SINK DETAILS

| Property | Details |
|----------------------------|------------|
| Material | Copper |
| Finish | Tin Plated |
| Device Attachment Options | - |
| Thermal Interface Material | - |

| Property | Details |
|------------------------------|------------|
| Heat Sink Width (mm) | 8 |
| Heat Sink Length (mm) | 10.16 |
| Heat Sink Height (mm) | 22.86 |
| Heat Sink Mounting Direction | Horizontal |

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)



Note: The thickness of the drain pad is variable depending on the amount of heat generated by the SMT device, design, limitations and process. This is the exposed printed circuit.

